



## BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	20.1000 mm x 35.1000 mm		
Min track/spacing:	0.1524 mm / 0.1524 mm	Min hole diameter:	0.2540 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm		4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

### HugonLabs

Sheet:  
File: bessefilter.kicad\_pcb

### Title: LC Filter 3rd Order

Size: USLetter	Date: 2022-03-14	Rev: 1.0
KiCad E.D.A.	kicad 6.0.2-378541a8eb-116-ubuntu20.04.1	Id: 1/1